

Part: IRG8CH37K10F

Description: 1200V UltraFast Switching IGBT Die available in Wafer Uncut, Die on Film, or Waffle Pack

Support Docs: [Datasheet](#)

Specifications	
Parameter	Value
Package	Die
Switching Speed	Low-Vceon
V _{CES} (V)	1200
I _C @ 100C (A)	35
V _{CE(ON)} @25C typ (V)	1.70
V _{CE(ON)} @25C max (V)	2.10

Packaging Options					
Product ID	Description	Status	Standard Pack	1K Budgetary Pricing (USD)	Qty
IRG8CH37K10F	A IRG8CH37K10F with Standard Packaging	Active	1		<input type="text" value="1"/> ADD TO CART

Package Support Docs

IR can offer a range of carrier options to suit individual customer needs. As standard, we offer [probed Die on wafer](#), [sawn Die on film](#) and in [waffle tray / chip pack](#).

For certain Die products, Tape and Reel, in the form of [Pocket Tape](#) is available. Please use our [online help utility](#) for details.

Details on the advantages/disadvantages of the various carrier options can be found in the application note on [carrier options](#) or the links [above](#).



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